Monday 3 October

- 9:30–12:30: 13th European FIB Users Group Meeting, EFUG workshop
- 14:00–15:40: EFUG workshop / Workshop "Reliability in harsh environment"
- 15:40–16:00: Coffee break
- 16:00–18:00: EFUG workshop / Workshop "Reliability in harsh environment"

Tuesday 4 October

- 8:30–13:00: Workshop "Packaging and FA Techniques of Optoelectronic Devices for aeronautic and Space Applications" in conjunction with ISROS (in auditorium of IMS Lab)
- 8:50–10:30: **Tutorial** "Advanced CMOS - Application of reliability models in circuit design"
- 10:30–10:50: Coffee break
- 10:50–12:30: **Tutorial** "Fault Isolation in Semiconductor Product, Process, Physical and Package FA" / **Tutorial** "GaN-HEMTs parasitics and Reliability"
- 12:30–14:00: Lunch
- 14:00–14:20: Conf. Opening
- 14:20–15:00: **Invited** "Perf, Reliability and Variability in sub-45nm CMOS Technologies"
- 15:00–15:40: Best Paper IRPS / Best Paper IPFA
- 15:40–16:00: Coffee break
- 16:00–17:20: Session A : Quality & Reliability Techniques for Devices and Systems / Session F2: Aeronautic and Spatial electronics: robustness and reliability issues
- 17:20–18:20: Presentation of Exhibitors
- 18:20–20:00: Cocktail offered by Exhibitors

Wednesday 5 October

- 8:30–10:50: Session D1: Failure Mechanisms in High Bandgap Devices and HBTs — **Invited** "Reliability issues of GaN based high voltage power devices"
- 9:10–10:50: Session F1: Design for reliability of power devices
- 10:50–11:10: Coffee break
- 11:10–12:50: Session D-F: Modelling for power devices reliability — **Invited** "Accelerated Testing under Complex Loading Conditions: Benefits and Challenges"
- Session A: Quality & Reliab. Techniques for Devices and Systems
- 12:50–14:00: Lunch
- 14:00–16:20: Session D2: Failure Mechanisms in Photonic Devices — **Invited** "Do we understand the degradation mechanisms of InGaN laser diode?"
- 14:40–16:20: Session F-E: Modelling for power devices reliability
- 16:20–16:40: Coffee break
- 16:40–18:00: Poster session
- 18:00–19:30: Workshop EUFANET

Thursday 6 October

- 8:30–10:30: Session B3: EOS/ESD events and impact from system to device — **Invited** "Transient Interferometric Mapping for ESD and latch-up analysis"
- 9:10–10:30: Session E1: Packaging Reliability
- 10:30–10:50: Coffee break
- 10:50–12:50: Session C1: Advanced Techniques for failure analysis and Case studies: EOBT — **Invited** "From Component to System Failure Analysis – the future challenge within work-sharing supply chains"
- 11:30–12:50: Session E1: Packaging Reliability
- 12:50–14:00: Lunch
- 14:00–16:20: Session B1: Failure Mechanisms in Si technologies and Nanoelectronics: Hot carriers, high K, ... — **Invited** "HCI and NBTI Induced Degradation and Impacts on Circuits Aging in Gate-all-Around Silicon Nanowire Transistors"
- 14:40–16:20: Session C2: Advanced Techniques for failure analysis and Case studies
- 16:20: Coffee break
- 17:00: Bus departure to a wine area and gala dinner

Friday 7 October

- 8:30–10:10: Session E3: MEMS Reliability — **Invited** "Dielectric charging phenomenon in electrostatically driven MEMS/NEMS devices: Nanoscale and macroscale characterization using novel assessment
- 9:10–10:10: Session B2: Electromigration and simulation
- 10:10–10:30: Coffee break
- 10:30–12:30: Session C1: Advanced Techniques for failure analysis and Case studies: EOBT — **Invited** "The combinational usage of the laser SQUID microscope, the laser terahertz emission microscope, and fault simulations in non-electrical-
- 11:10: Session E2: Reliability of Interconnections
- 12:30–13:00: BPA and closing